
AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method for preventing contamination after plating a metal or an alloy on a surface of a substrate comprising:
- a) providing a plating solution on the surface of the substrate;
 - b) electroplating or electrolysis plating the metal or alloy on the surface of the substrate; and,
 - c) introducing a second solution comprising a stabilizing agent, the stabilizing agent comprising an acid which keeps metal or alloy ions in the plating solution.
2. (Original) Method according to claim 1, wherein in said introducing step (c) the stabilizing agent prevents formation of precipitated salts on the surface of the substrate.
3. (Currently Amended) Method according to claim 1, wherein the stabilizing agent further comprises an aqueous solution of a complexing agent for the plating metals.
4. (Original) Method according to claim 3, wherein the complexing agent comprises an organic or inorganic compound.
5. (Original) Method according to claim 3, wherein the complexing agent comprises a mixture of an organic compound and an inorganic compound.
6. (Original) Method according to claim 3, wherein the aqueous solution of the complexing agent for the plating metals comprises Citrate, Acetate, EDTA, or Ammonia.

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7. (Original) Method according to claim 6, wherein in said introducing step (c) at least one of the aqueous solutions of the complexing agent is introduced in the following concentrations:

Citrate in a preferred concentration of about 0.5 to about 1.0 mol/kg,

Acetate in a preferred concentration of about 0.5 mol/kg,

EDTA in a preferred concentration of about 0.2 to about 0.5 mol/kg, and/or

Ammonia in a preferred concentration of about 0.1 to about 1.0 mol/kg.

8. (Canceled) Method according to claim 1, wherein the stabilizing agent comprises an acid.
9. (Currently Amended) Method according to claim 8 1, wherein the acid does not form a low-soluble salt with the plated metals.
10. (Currently Amended) Method according to claim 8 1, wherein the acid further comprises an organic ~~or inorganic~~ compound.
11. (Canceled) Method according to claim 8, wherein the acid comprises a mixture of an organic compound and an inorganic compound.
12. (Currently Amended) Method according to claim 8 1, wherein the acid comprises aqueous solutions of Hydrochloric Acid, ~~Sulfuric Acid~~, or Phosphoric Acid.

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13. (Currently Amended) Method according to claim 12, wherein in said introducing step (c) at least one of the aqueous solutions is introduced in the following concentrations:

Hydrochloric Acid in a preferred concentration of about 0.1 mol/kg,

Hydrochloric Acid in a preferred concentration of about 0.01 mol/kg,

Sulfuric Acid in a preferred concentration of about 0.05 mol/kg; and/or

Phosphoric Acid in a preferred concentration of about 0.1 mol/kg.

14. (Canceled) Method according to claim 1, wherein the stabilizing agent comprises a mixture of an aqueous solution of a complexing agent for the plating metals and an acid.
15. (Original) Method according to claim 1, wherein the stabilizing agent is contained in the plating solution.
16. (Original) Method according to claim 1, wherein the substrate comprises a semiconductor wafer.

Claims 17-32 (Withdrawn)

33. (Currently Amended) In a method for plating a metal alloy on a surface of a substrate by electrolytic activity using a plating solution on the surface wherein the improvement comprises introducing a second solution comprising a stabilizing agent onto the substrate surface, the stabilizing agent comprising an acid in order to keep metal alloy ions in the plating solution.

34. (New) Method according to claim 1, wherein the stabilizing agent comprises sulfuric acid and EDTA.

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